REMARKS

Applicant highly appreciates the allowance of claims 10-15.

Claim Objections

Claims 1 and 11 are objected because of informalities.

In response, Applicant amends claims 1, 10 and 11 to overcome the objection. The amendment is made based on Examiner's guidance.

Claim Rejections – 35 USC § 102 & 103

Claims 1-4 are rejected under 35 U.S.C. 102(e) as being anticipated by Ootori et. al. (U.S. Patent No. 6,516,867). Claim 5 is rejected under 35 U. S. C 103 (a) as being unpatentable over Ootori et. al. (U.S. Patent No. 6,516,867). Claims 6-9 are objected because of depending on rejected claims. Applicant disagrees with Examiner's rejection and traverses it as below.

As regards claim 1, the feature that **a pair of symmetrical forming parts** is slidably engaged in the base part is clearly defined. However, Ootori et. al. reference discloses the heat sink manufacturing device consists of a fixed mold 2, a movable mold 3 and a slide mold 4 which can move in the horizontal direction. Ootori reference discloses the slide mold 4 has two parts that extend in the horizontal direction and are separated from one another for forming fins of various in shape (particularly see Col. 5 lines 19-27). Thus, from Ootori reference, there is only one slide mold 4 at one side of the heat sink manufacturing device, which does not teach the pair of symmetrical forming parts of the present invention.

Claim 1 further points out **each of the forming parts has a recess in communication with the cavity corresponding to the heat pipe and one portion of the recesses extending transversely the slots.** In contrast, Ootori reference discloses a mold has a groove where the heat pipe is to be placed in the rear surface of the base (particularly see Col. 6 lines 7-11). Therefore, from Ootori reference, the groove of the mold for the heat pipe is defined in the fixed mold 2. So, Ootori reference does not teach the recesses defined in the forming parts for the heat pipe. Furthermore, claim 1 of the invention defines that a **core is accommodated in the recess of the forming parts.** However, in Ootori reference, the groove defined in the mold is adapted for placing the heat pipe therein but not for forming the heat pipe; accordingly, no core for forming the heat pipe is accommodated in the groove of the mold of Ootori reference. Therefore, Ootori reference does not teach the core of claim 1 of the present application.

In conclusion, Ootori reference does not anticipate claim 1 of the present application, because Ootori reference does not teach all limitations of claim 1. Claim 1 meets the patentability requirement under 35 U. S. C. 102. Claim 1 thus should be allowable, and its dependent claims 2-9 should also be allowable.

New claim 19 is a combination of original claims 1, 2 and 6, which is deemed by Examiner as patentable over the prior art in record. Accordingly new claim 19 is allowable. New claims 20-23 should also be allowable since each of them includes the novel features of new claim 19.

In view of the foregoing, the subject application as claimed in the pending claims is in a condition for allowance and an action to such effect is earnestly

solicited.

Respectfully submitted,

Liu et al.

By _____
Wei Te Chung

Registration No.: 43,325

Foxconn International, Inc.

P. O. Address: 1650 Memorex Drive, Santa Clara, CA 95050

Tel No.: (408) 919-6137